# DF6A6.8FUT

# **Quad Array for ESD Protection**

This quad voltage suppressor is designed for applications requiring transient overvoltage protection capability. It is intended for use in voltage and ESD sensitive equipment such as computers, printers, business machines, communication systems, medical equipment, and other applications. Its quad junction common anode design protects four separate lines using only one package. These devices are ideal for situations where board space is at a premium.

### **Specification Features**

- SC-88 Package Allows Four Separate Unidirectional Configurations
- Low Leakage < 1 μA @ 5 Volt
- Breakdown Voltage: 6.4 7.2 Volt @ 5 mA
- Low Capacitance (40 pF typical)
- ESD Protection Meeting 61000-4-2 Level 4 and 16 kV Human Body Model
- These are Pb-Free Devices

#### **Mechanical Characteristics**

- Void Free, Transfer-Molded, Thermosetting Plastic Case
- Corrosion Resistant Finish, Easily Solderable
- Package Designed for Optimal Automated Board Assembly
- Small Package Size for High Density Applications

## **MAXIMUM RATINGS** (T<sub>A</sub> = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Power Dissipation @ 8 x 20 μs (Note 1)	P <sub>pk</sub>	75	Watts
Steady State Power Dissipation (Note 2)	P <sub>D</sub>	385	mW
Thermal Resistance – Junction-to-Ambient Derate Above 25°C	$R_{ hetaJA}$	328 3.0	°C/W mW/°C
Maximum Junction Temperature	T <sub>Jmax</sub>	150	°C
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	–55 to +150	°C
ESD Discharge MIL STD 883C – Method 3015–6 IEC61000–4–2, Air Discharge IEC61000–4–2, Contact Discharge	V <sub>PP</sub>	16 16 8	kV
Lead Solder Temperature (10 seconds duration)	T <sub>L</sub>	260	°C

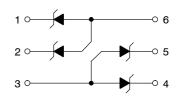
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- 1. Per Waveform Figure 1
- 2. Mounted on FR-5 Board = 1.0 X 0.75 X 0.062 in.



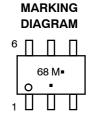
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**CASE 419B-02** 



68 = Specific Device Code

M = Date Code

= Pb-Free Package

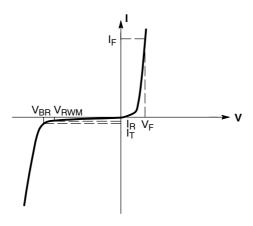
(Note: Microdot may be in either location.)

#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
DF6A6.8FUT1G	SC-88 (Pb-Free)	3000/Tape & Reel
DF6A6.8FUT2G	SC-88 (Pb-Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

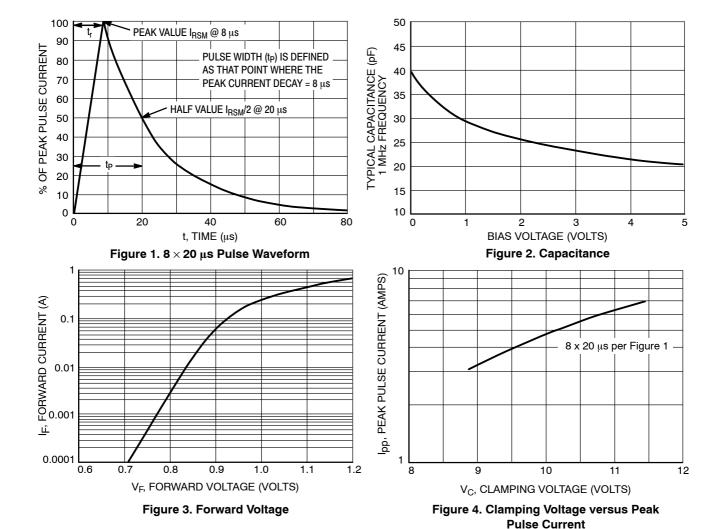
# DF6A6.8FUT



V-I Curve

## **ELECTRICAL CHARACTERISTICS**

	Device	Breakdown Voltage V <sub>BR</sub> @ 5 mA (Volts)		Leakage Current I <sub>RM</sub> @ V <sub>RWM</sub> = 5 V	Typical Capacitance @ 0 V Bias	Max V <sub>F</sub> @ I <sub>F</sub> = 10 mA	Max Z <sub>Z</sub> @ 5 mA	Max Z <sub>ZK</sub> @ 0.5 mA	
Device	Marking	Min	Nom	Max	(μΑ)	(pF)	(V)	(Ω)	(Ω)
DF6A6.8FUT1G	68	6.4	6.8	7.2	1.0	40	1.25	30	300
DF6A6.8FUT2G	68	6.4	6.8	7.2	1.0	40	1.25	30	300



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## DF6A6.8FUT

#### PACKAGE DIMENSIONS

## SC-88/SC70-6/SOT-363 CASE 419B-02 **ISSUE W**

NOTES

**A** 0.80

АЗ

DIMENSIONING AND TOLERANCING PER ANSI

419B-01 OBSOLETE, NEW STANDARD 419B-02.

DIM MIN NOM MAX MIN NOM MAX

 b
 0.10
 0.21
 0.30
 0.004
 0.008
 0.012

 C
 0.10
 0.14
 0.25
 0.004
 0.005
 0.010

 D
 1.80
 2.00
 2.20
 0.070
 0.078
 0.086

 C
 1.41
 4.07
 0.04
 0.001
 0.027

L 0.10 0.20 0.30 0.004 0.008 0.012 H<sub>F</sub> 2.00 2.10 2.20 0.078 0.082 0.086

1.15 1.25 1.35 0.045 0.049 0.053

0.95 1.10 0.031 0.037 0.043 **A1** 0.00 0.05 0.10 0.000 0.002 0.004

INCHES

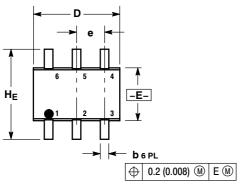
0.008 REF

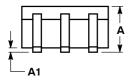
0.026 BSC

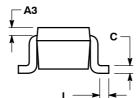
Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

**MILLIMETERS** 

0.20 REF







#### **SOLDERING FOOTPRINT\***

# 0.50 0.0197 0.65 0.025 0.65 0.025 0.40 0.0157 1.9 0.0748 mm

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

SCALE 20:1

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